

# 8301AB

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## characteristics

Polyurethane 8301AB synthesis, the products produced have high-quality flexibility and low-temperature resistance, cured products crystal clear, highly transparent, suitable for room temperature or heating curing.

## Areas of application

Polyurethane 8301AB can be widely used for encapsulation of nameplates, LEDs and electronic circuit boards.

## Technical Parameters

	A glue 8301A	Curing agent 8301B
<b><u>COLOR</u></b>	Colorless to light yellow liquid	Colorless to light yellow liquid
<b>Density(g/m<sup>3</sup>)</b>	1.02±0.05	<u>1.04</u> ±0.05
<b>Viscosity(mPa·s)</b>	<u>700cps</u>	600maxcps
<b>Brookfield DV2TRV test method</b>	25℃	
<b>Mixing ratio (by weight)</b>	100 : 100	
<b>(by volume)</b>	1 : 1	

## post-blending

	Main agent + curing agent
<b>Status</b>	<b>fluids</b>

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The above performance data are typical data measured in a laboratory environment with a temperature of 25℃ and a humidity of 70%, and are for customers' reference only.

<b>Viscosity</b>	<b>550±50mPa.S</b>
<b>Brookfield DV2TRV test method</b>	<b>25℃</b>
<b>Operating time(100g, 25℃)</b>	<b>20±3 min</b>
<b>Brookfield DV2TRV test method, Highest viscosity 800mPa·s</b>	
<b>utilization rate</b>	<b>280-350 g/m<sup>2</sup>(depending on the substrate)</b>

### **Curing time**

<b>Initial curing</b>	<b>Approx. 24 hours at room temperature</b>
<b>Final curing</b>	<b>Approx. 48 hours at room temperature</b>
<b>Temperature range</b>	<b>10℃-70℃</b>

### **Usage**

#### **working environment**

Please keep the glue container clean, and mix the A and B components strictly according to the weight ratio, weigh accurately, and stir well clockwise along the inner wall of the container, and then leave it to stand for 3-5 minutes before use.

#### **caveat**

According to the operating time and the amount of glue mixing to avoid waste. When the temperature is lower than 15 ℃, please preheat the A glue to 30 ℃ before glue mixing, easy to operate (low temperature A glue will thicken); after use must be sealed barrel lid, to avoid moisture absorption caused by the product scrap. When the relative humidity is greater than 85%, the surface of the cured material is easy to absorb the moisture in the air, forming a layer of white mist, so when the

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### Test results

<b><u>Durometer</u></b>	shoreD	65
<b><u>Bending strength</u></b>	Kg/mm <sup>2</sup>	<b><u>23</u></b>
Heat distortion temperature	°C	140
Water absorption	%	<0.15
<b><u>Compressive strength</u></b>	Kg/mm <sup>2</sup>	13.4

### Save

Whether the product is afraid of cold	Yes	
moisture sensitivity	organosilicon	curing agent
	NO	sensitivities
Recommended Storage Temperature	15°C-25°C(not lower than 10°C and not higher than 50°C)	
validity period	2 months in original packaging	
<b><u>wrap</u></b>	A glue	curing agent
	5kg/pot	5kg/pot

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